




<div>MICROCHIP</div>						Package Homogeneous Materials					
Semiconductor Device Type: RXX VQFN_24_4x4x0.9mm_MatteTin											
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	15.04	(mg) Total	Mold Compound	% of Total Weight	36.45	
Silicon	7440-21-3	Chip (Die)	3.30	1.36	33030	G700	Epoxy resin	Trade Secret	7.70		
Zinc	7440-66-6	Leadframe	0.07	0.03	711		Phenol Resin	Trade Secret	7.30		
Iron	7439-89-6	Leadframe	1.34	0.55	13370		Silica(Amorphous) A	60676-86-0	73.80		
Phosphorus	7723-14-0	Leadframe	0.05	0.02	469		Silica(Amorphous) B	7631-86-9	11.00		
Copper	7440-50-8	Leadframe	55.44	22.88	554384		Carbon Black	1333-86-4	0.20		
Silver	7440-22-4	Leadframe	1.47	0.61	14733	Total 100.00					
Silver	7440-22-4	Die Attach	0.86	0.36	8624	24.09 C194	(mg) Total	Leadframe	% of Total Weight	58.37	
bisphenol-F-(epichlorohydrin)	9003-36-5	Die Attach	0.03	0.01	345		Zinc	7440-66-6	0.12		
Fatty acids, C18-unsatd., dimers, polymers with epichlorohydrin	68475-94-5	Die Attach	0.02	0.01	230		Iron	7439-89-6	2.29		
gamma-Butyrolactone	96-48-0	Die Attach	0.04	0.02	425		Phosphorus	7723-14-0	0.08		
Epoxy resin	Trade Secret	Die Attach	0.05	0.02	494		Copper	7440-50-8	94.98		
Poly[oxy(methyl-1,2-ethanediyl)], a-(2-aminomethylethyl)-w-(2-aminomethylethoxy)	9046-10-0	Die Attach	0.08	0.03	759	Ag plating	Silver	7440-22-4	2.52		
Copper oxide	1317-38-0	Die Attach	0.06	0.02	575		Total 100.00				
1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	Die Attach	0.005	0.002	46		0.47 8290	(mg) Total	Die Attach	% of Total Weight	1.15
Epoxy resin	Trade Secret	Mold Compound	2.81	1.16	28064			Silver	7440-22-4	75.00	
Phenol Resin	Trade Secret	Mold Compound	2.66	1.10	26606			bisphenol-F-(epichlorohydrin)	9003-36-5	3.00	
Silica(Amorphous) A	60676-86-0	Mold Compound	26.90	11.10	268980	Fatty acids, C18-unsatd., dimers, polymers with epichlorohydrin		68475-94-5	2.00		
Silica(Amorphous) B	7631-86-9	Mold Compound	4.01	1.65	40092	gamma-Butyrolactone		96-48-0	3.70		
Carbon Black	1333-86-4	Mold Compound	0.07	0.03	729		Epoxy resin	Trade Secret	4.30		
Copper	7440-50-8	Bonding Wire	0.28	0.12	2787		Poly[oxy(methyl-1,2-ethanediyl)], a-(2-aminomethylethyl)-w-(2-aminomethylethoxy)				
Palladium	7440-05-3	Bonding Wire	0.01	0.003	80						
Silver	7440-22-4	Bonding Wire	0.000005	0.000002	0						
Tin	7440-31-5	Lead Finish Plating	0.45	0.18	4464			Copper oxide	1317-38-0	5.00	
TOTALS:			100.00	41.27	1,000,000			1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	0.40	
41.27 mg Total Mass			Total 100.00								

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1.36	Total (mg)	Chip (Die)	% of Total Weight	3.30
Silicon	Silicon	7440-21-3	100.00	
Total			100.00	
0.12	(mg) Total	Bonding Wire	% of Total Weight	0.29
PD COATED CU Wire	Copper	7440-50-8	97.20	
	Palladium	7440-05-3	2.80	
	Silver	7440-22-4	0.00	
Total			100.00	
0.18	(mg) Total	Lead Finish Plating	% of Total Weight	0.45
Tin plating	Tin	7440-31-5	100.00	
Total			100.00	